

# 3.5x2.8 mm SMD CHIP LED LAMP

APED3528MBC

BLUE

## Features

- SINGLE COLOR.
- SUITABLE FOR ALL SMT ASSEMBLY AND SOLDER PROCESS.
- IDEAL FOR BACKLIGHTING.
- AVAILABLE ON TAPE AND REEL.
- PACKAGE : 500PCS / REEL.

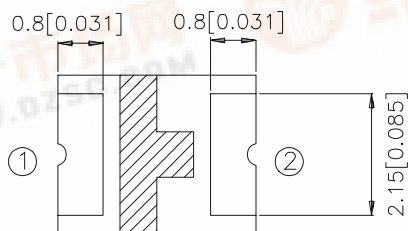
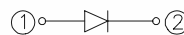
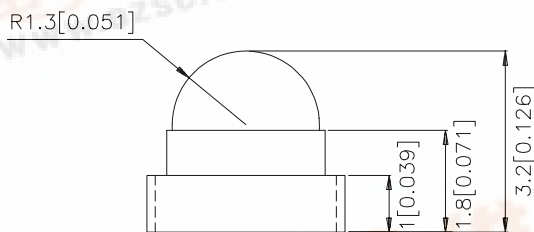
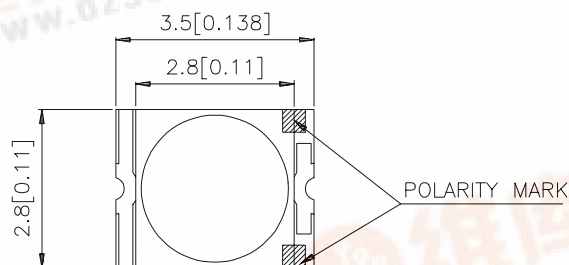
## Description

The Blue source color devices are made with GaN on SiC Light Emitting Diode.

Static electricity and surge damage the LEDS. It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.

All devices, equipment and machinery must be electrically grounded.

## Package Dimensions



### Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is  $\pm 0.2$  (0.0079") unless otherwise noted.
3. Specifications are subject to change without notice.



## Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) @ 20 mA		Viewing Angle
			Min.	Typ.	2θ1/2
APED3528MBC	BLUE (GaN)	WATER CLEAR	7	40	40°

Note:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

## Electrical / Optical Characteristics at T<sub>A</sub>=25°C

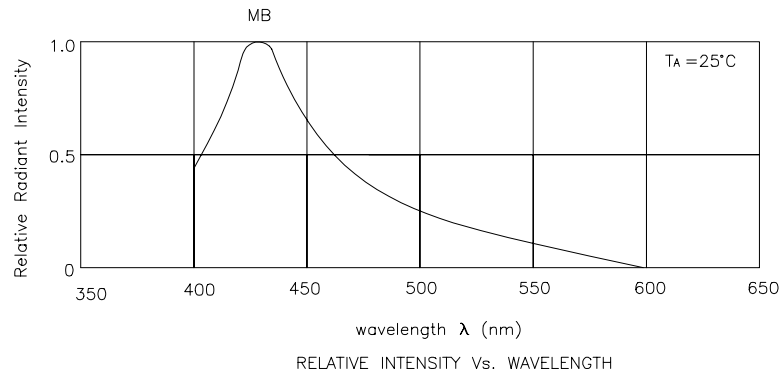
Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λ <sub>peak</sub>	Peak Wavelength	Blue	430		nm	I <sub>F</sub> =20mA
λ <sub>D</sub>	Dominate Wavelength	Blue	466		nm	I <sub>F</sub> =20mA
Δλ <sub>1/2</sub>	Spectral Line Half-width	Blue	60		nm	I <sub>F</sub> =20mA
C	Capacitance	Blue	100		pF	V <sub>F</sub> =0V;f=1MHz
V <sub>F</sub>	Forward Voltage	Blue	3.8	4.5	V	I <sub>F</sub> =20mA
I <sub>R</sub>	Reverse Current	Blue		10	μA	V <sub>R</sub> = 5V

## Absolute Maximum Ratings at T<sub>A</sub>=25°C

Parameter	Blue	Units
Power dissipation	105	mW
DC Forward Current	30	mA
Peak Forward Current [1]	150	mA
Reverse Voltage	5	V
Operating / Storage Temperature	-40°C To +85°C	

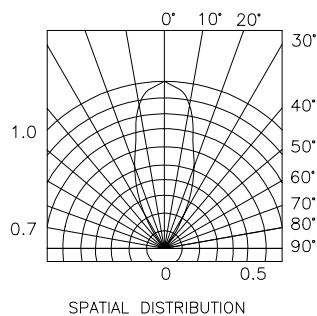
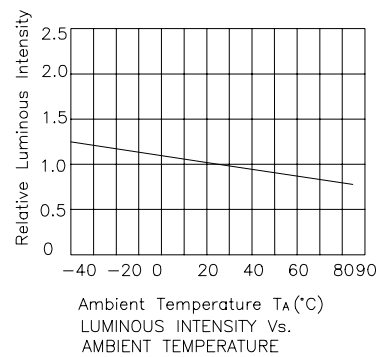
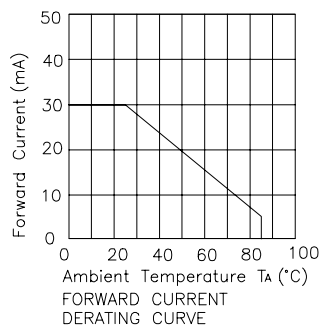
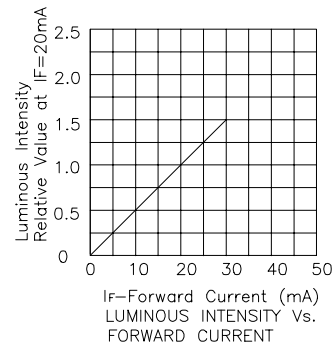
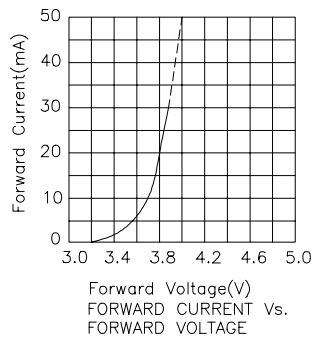
Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.



Blue

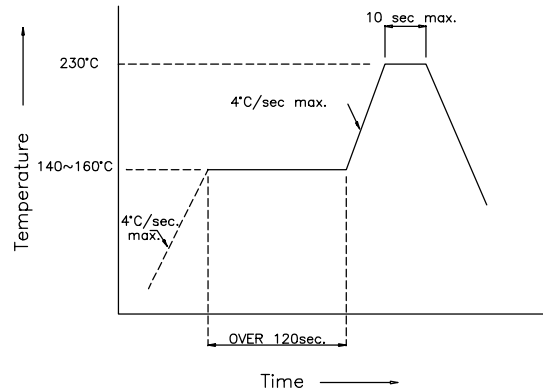
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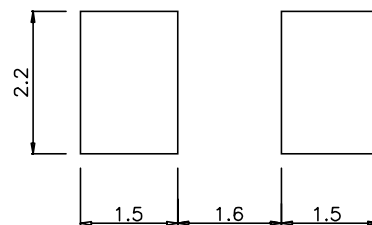
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### SMT Reflow Soldering Instructions

Number of reflow process shall be less than 2 times and cooling process to normal temperature is required between first and second soldering process.



### Recommended Soldering Pattern (Units : mm)



### Tape Specifications (Units : mm)

